



BT15T120ANF

General Description:

Using HUAJING's proprietary trench design and advanced FS(field stop) technology, the 1200V Trench FS-IGBT offers superior conduction and switching performances, high avalanche ruggedness.

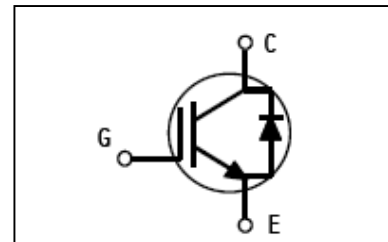
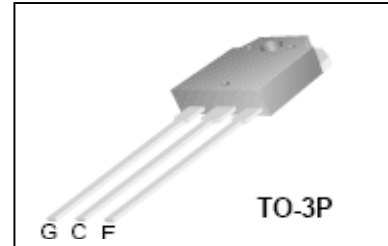
Features:

- I Trench FS Technology, Positive temperature coefficient
- I Low saturation voltage: $V_{CE(sat)}$, typ = 1.95V
@ $I_C = 15A$ and $T_C = 25^\circ C$
- I Extremely enhanced avalanche capability

Applications:

Power switch circuit of induction cooker(IH).

| | | |
|--------------------------------|------|---|
| V_{CES} | 1200 | V |
| I_C | 15 | A |
| P_{tot} ($T_C=25^\circ C$) | 186 | W |
| $V_{CE(SAT)}$ | 1.95 | V |



Absolute Maximum Ratings

($T_c = 25^\circ C$ unless otherwise specified):

| Symbol | Parameter | Rating | Units |
|----------------|--|-------------|-------|
| V_{CES} | Collector-Emitter Voltage | 1200 | V |
| V_{GES} | Gate- Emitter Voltage | ± 20 | V |
| I_C | Collector Current | 30 | A |
| | Collector Current @TC = 100 °C | 15 | A |
| I_{CM}^{al} | Pulsed Collector Current | 45 | A |
| I_F | Diode Continuous Forward Current @TC = 100 °C | 15 | A |
| I_{FM} | Diode Maximum Forward Current | 45 | A |
| P_D | Power Dissipation @ TC = 25°C | 186 | W |
| | Power Dissipation @TC = 100 °C | 74 | W |
| T_J, T_{stg} | Operating Junction and Storage Temperature Range | -55 to +150 | °C |
| T_L | Maximum Temperature for Soldering | 300 | °C |

Thermal Characteristics

| Symbol | Parameter | Typ. | Max. | Units |
|-----------------|--|------|------|-------|
| $R_{\theta JC}$ | Thermal Resistance, Junction to case for IGBT | 0.55 | 0.8 | °C/W |
| $R_{\theta JC}$ | Thermal Resistance, Junction to case for Diode | 1.0 | 2 | °C/W |



BT15T120ANF



| | | | | |
|-----------------|---|----|----|-----------------------------|
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient | 35 | 40 | $^{\circ}\text{C}/\text{W}$ |
|-----------------|---|----|----|-----------------------------|

Electrical Characteristics of the IGBT ($T_c = 25^{\circ}\text{C}$ unless otherwise specified):

| OFF Characteristics | | | | | | |
|---------------------|-------------------------------------|---|--------|------|------|-------|
| Symbol | Parameter | Test Conditions | Rating | | | Units |
| | | | Min. | Typ. | Max. | |
| V_{CES} | Collector-Emitter Breakdown Voltage | $V_{GE}=0\text{V}, I_{CE}=250\mu\text{A}$ | 1200 | -- | -- | V |
| I_{CES} | Collector-Emitter Leakage Current | $V_{GE}=0\text{V}, V_{CE}=V_{CES}$ | -- | -- | 1.0 | mA |
| $I_{GES(F)}$ | Gate to Emitter Forward Leakage | $V_{GE}=+20\text{V}$ | -- | -- | +250 | nA |
| $I_{GES(R)}$ | Gate to Source Reverse Leakage | $V_{GE}=-20\text{V}$ | -- | -- | -250 | nA |

| ON Characteristics | | | | | | |
|--------------------|--------------------------------------|-------------------------------------|--------|------|------|-------|
| Symbol | Parameter | Test Conditions | Rating | | | Units |
| | | | Min. | Typ. | Max. | |
| $V_{CE(sat)}$ | Collector-Emitter Saturation Voltage | $I_C=15\text{A}, V_{GE}=15\text{V}$ | -- | 1.95 | 2.5 | V |
| $V_{GE(TH)}$ | Gate Threshold Voltage | $I_C=250\mu\text{A}, V_{CE}=V_{ge}$ | 4.5 | 6.2 | 7.5 | V |

Pulse width $t_p \leq 380\mu\text{s}, \delta \leq 2\%$

| Dynamic Characteristics | | | | | | |
|-------------------------|------------------------------|--|--------|------|------|-------|
| Symbol | Parameter | Test Conditions | Rating | | | Units |
| | | | Min. | Typ. | Max. | |
| C_{ies} | Input Capacitance | $V_{CE}=30\text{V}, V_{GE}=0\text{V}$ $f=1\text{MHz}$ | -- | 2526 | -- | pF |
| C_{oes} | Output Capacitance | | -- | 52 | -- | |
| C_{res} | Reverse Transfer Capacitance | | -- | 29 | -- | |

| Resistive Switching Characteristics | | | | | | |
|-------------------------------------|--------------------------|---|--------|------|------|-------|
| Symbol | Parameter | Test Conditions | Rating | | | Units |
| | | | Min. | Typ. | Max. | |
| $t_{d(ON)}$ | Turn-on Delay Time | $V_{CE}=600\text{V}, I_C=15\text{A}$ $V_{GE}=15\text{V}, R_g=10\Omega$ Inductive Load | -- | 15 | -- | ns |
| t_r | Rise Time | | -- | 16 | -- | |
| $t_{d(OFF)}$ | Turn-Off Delay Time | | -- | 70 | -- | |
| t_f | Fall Time | | -- | 160 | -- | |
| E_{on} | Turn-On Switching Loss | | -- | 0.9 | -- | mJ |
| E_{off} | Turn-Off Switching Loss | | -- | 0.5 | -- | |
| E_{ts} | Total Switching Loss | | -- | 1.4 | -- | |
| Q_g | Total Gate Charge | $V_{CE}=600\text{V}, I_C=15\text{A}$ $V_{GE}=15\text{V}$ | -- | 92.5 | -- | nC |
| Q_{ge} | Gate to Emitter Charge | | -- | 22.1 | -- | |
| Q_{gc} | Gate to Collector Charge | | -- | 37.6 | -- | |

Electrical Characteristics of the DIODE (T_c= 25°C unless otherwise specified):

| Symbol | Parameter | Test Conditions | Rating | | | Units |
|--|-------------------------------------|--------------------------------------|--------|------|------|-------|
| | | | Min. | Typ. | Max. | |
| V _{FM} | Diode Forward Voltage | I _F =15A | -- | 1.2 | 1.8 | V |
| T _{rr} | Reverse Recovery Time | I _F =15A di/dt=200A/uS | -- | 330 | 500 | ns |
| I _{rr} | Diode Peak Reverse Recovery Current | | -- | 30 | 50 | A |
| Q _{rr} | Reverse Recovery Charge | | -- | 5 | 10 | uC |
| Pulse width t _p ≤380μs,δ≤2% | | | | | | |

^{a1}: Repetitive rating; pulse width limited by maximum junction temperature

Typical Performance Characteristics

Figure 1. Saturation Voltage Characteristics

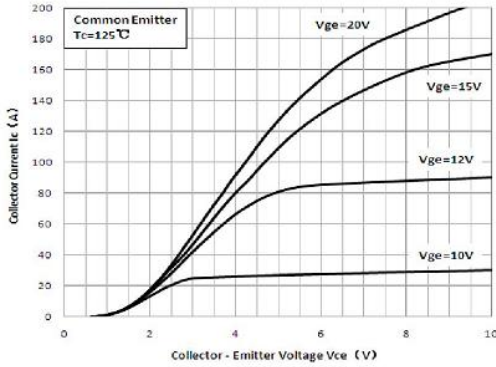


Figure 2. Saturation Voltage Characteristics

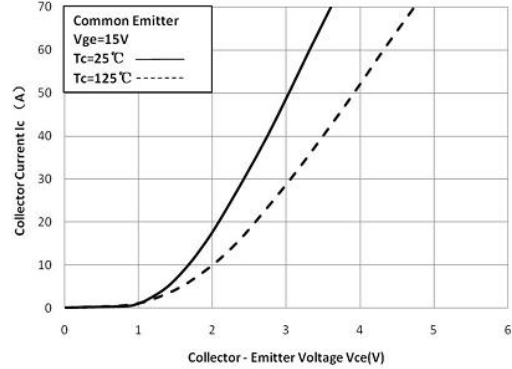


Figure 3. Saturation Voltage vs. Case Temperature

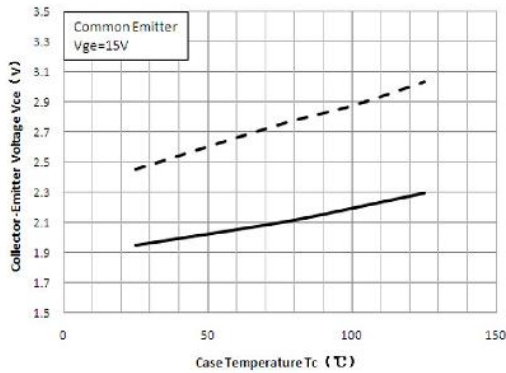


Figure 4. Saturation Voltage vs. VGE

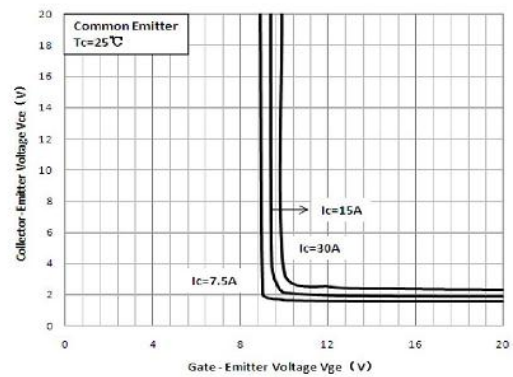


Figure 5. Saturation Voltage vs. VGE

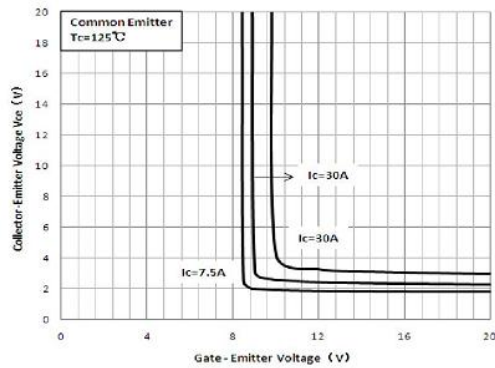


Figure 6. Capacitance Characteristics

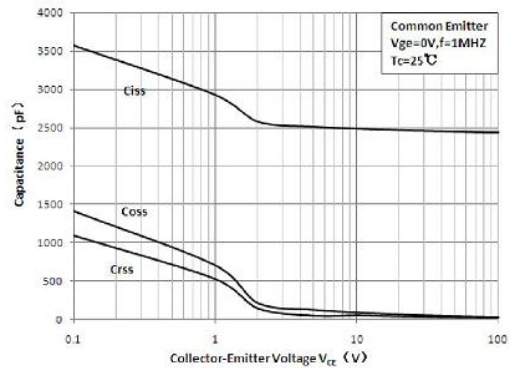


Figure 7. Turn-On Characteristics vs. Gate Resistance

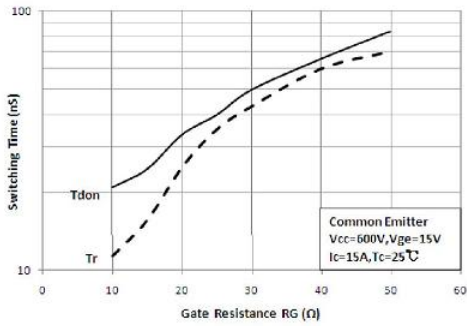


Figure 8. Turn-Off Characteristics vs. Gate Resistance

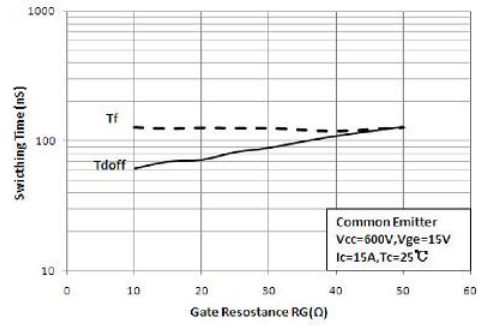


Figure 9. Switching Loss vs. Gate Resistance

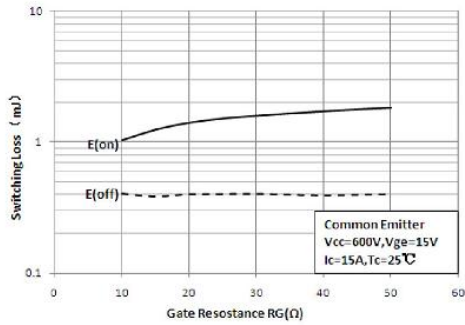


Figure 10. Turn-On Characteristics vs. Collector Current

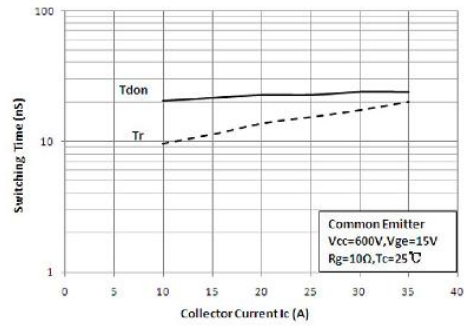


Figure 11. Turn-Off Characteristics vs. Collector Current

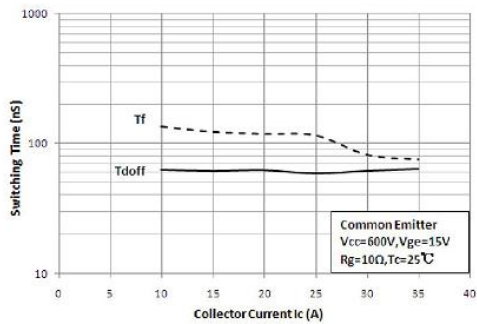


Figure 12. Switching Loss vs. Collector Current

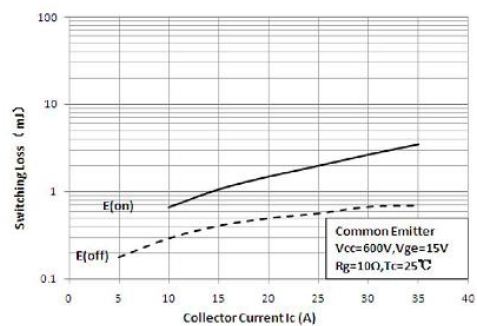


Figure 13. Forward Characteristics

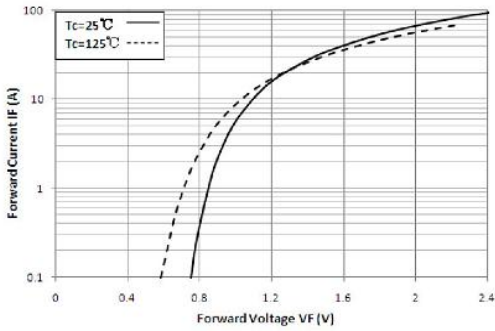


Figure 14. Reverse Recovery Current

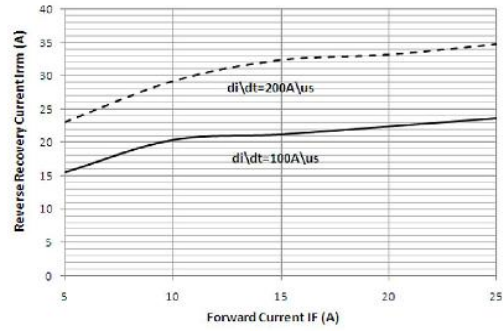


Figure 15. Reverse Recovery Time

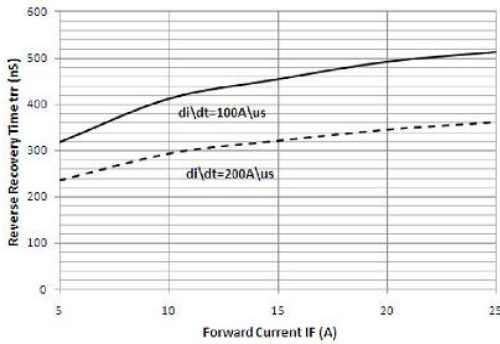
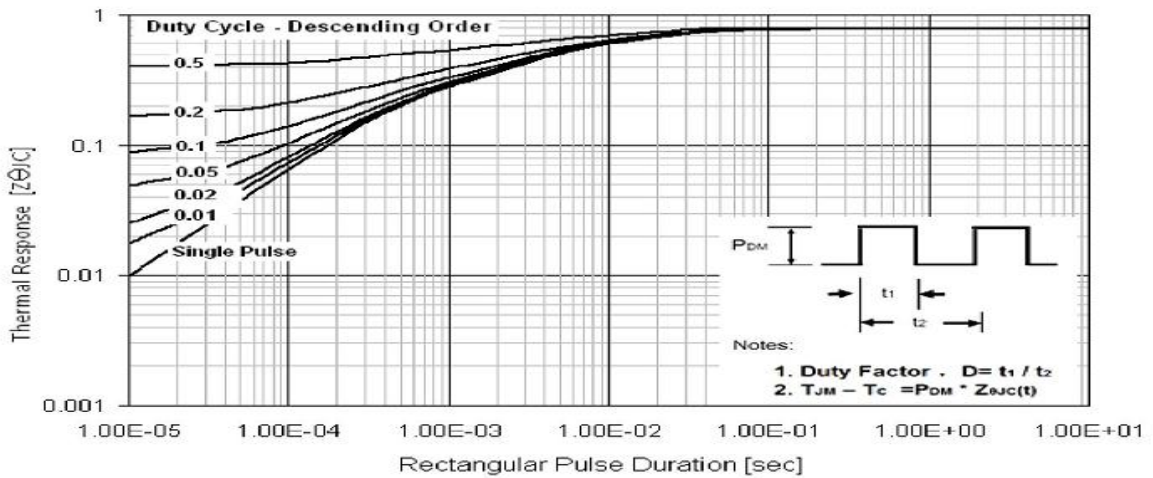
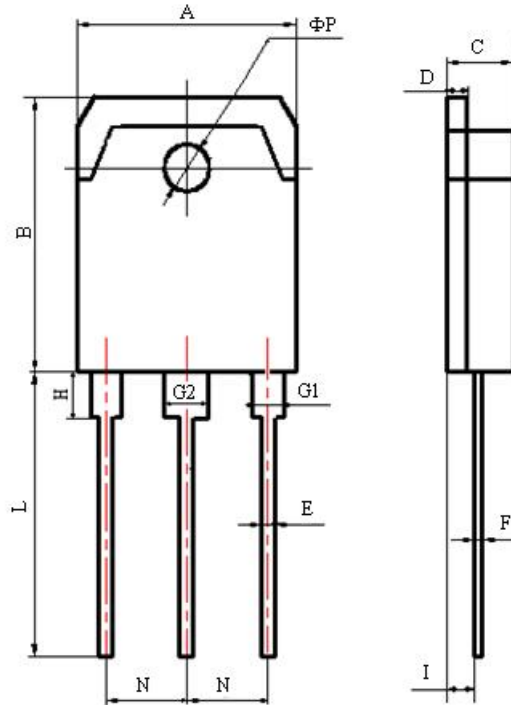


Figure 16. Transient Thermal Impedance of IGBT



Package Information:



| Items | Values(mm) | |
|-------|------------|-------|
| | MIN | MAX |
| A | 15.10 | 15.90 |
| B | 19.30 | 20.30 |
| C | 4.70 | 4.90 |
| D | 1.40 | 1.60 |
| E | 0.90 | 1.10 |
| F | 0.50 | 0.70 |
| G1 | 2.00 | 2.20 |
| G2 | 3.00 | 3.20 |
| H | 3.00 | 3.70 |
| I | 1.20 | 1.60 |
| | 2.70 | 2.90 |
| L | 19.00 | 21.00 |
| N | 5.25 | 5.65 |
| Φ P | 3.10 | 3.30 |

TO-3P(N) Package

The name and content of poisonous and harmful material in products

| Part's Name | Hazardous Substance | | | | | |
|------------------|---|-------|--------|--------|-------|-------|
| | Pb | Hg | Cd | Cr(VI) | PBB | PBDE |
| Limit | ≤0.1% | ≤0.1% | ≤0.01% | ≤0.1% | ≤0.1% | ≤0.1% |
| Lead Frame | ○ | ○ | ○ | ○ | ○ | ○ |
| Molding Compound | ○ | ○ | ○ | ○ | ○ | ○ |
| Chip | ○ | ○ | ○ | ○ | ○ | ○ |
| Wire Bonding | ○ | ○ | ○ | ○ | ○ | ○ |
| Solder | × | ○ | ○ | ○ | ○ | ○ |
| Note | Means the hazardous material is under the criterion of SJ/T11363-2006. Means the hazardous material exceeds the criterion of SJ/T11363-2006. The plumbum element of solder exist in products presently, but within the allowed range of Eurogroup's RoHS. | | | | | |

Warnings

1. Exceeding the maximum ratings of the device in performance may cause damage to the device, even the permanent failure, which may affect the dependability of the machine. It is suggested to be used under 80 percent of the maximum ratings of the device.
2. When installing the heatsink, please pay attention to the torsional moment and the smoothness of the heatsink.
3. IGBTs is the device which is sensitive to the static electricity, it is necessary to protect the device from being damaged by the static electricity when using it.
4. This publication is made by Huajing Microelectronics and subject to regular change without notice.

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